

Abstract
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The invention concerns a method for making a thin film, which consists in creating a brittle zone embedded by implantation of a chemical species in a substrate, so as to be able subsequently to provoke a fracture of the substrate along said brittle zone to separate therefrom said thin film. The invention is characterized in that the manufacturing method comprises in particular the following steps: a) a first implantation in the substrate at a first depth of a first chemical species; b) implanting at least one second chemical species in the substrate, at a second depth different from said first depth, and at a concentration higher than the concentration of the ~~main~~ first species, where the at least a second chemical species is less efficient than the ~~main~~ first chemical species for embrittling the substrate; c) diffusing at least part of said secondary species to the vicinity of the first depth; and d) initiating a fracture along the first depth. The invention also concerns the thin film obtained by the inventive method.